|                    |   | GROUP SHARP  | CORPORATION                                      | REPRESENTATIVE DIVISION                               |
|--------------------|---|--|--|---|
| 1-y.               | Doc. 1 79   | 3 SPECIFIC   | CATION   | OPTO-ELECTRONIC DEVICES                               |
| -                  | DEVICE  | SPECIFICATION FOR  | Applied:   | model name  |
|                    | VOL   | TAGE REGULATOR   | PQ015EZ01ZZ                                      | PQ015EZ01ZP   |
|                    | MODEL   |  | PQ018EZ01ZZ                                      | PQ018EZ01ZP   |
|                    |   |  | PQ025EZ01ZZ<br>PQ030EZ01ZZ                       | PQ025EZ01ZP<br>PQ030EZ01ZP                            |
|                    | {   | PQ***EZ01Z   | PQ033EZ01ZZ                                      | PQ033EZ01ZP   |
|                    |   | ·  |  |   |
| 1. These<br>Please | specification sheet<br>do not reproduce                   | s include materials protecte<br>or cause anyone to reproduc  | ed under copyright of S<br>ce them without Sharp | Sharp Corporation ("Sharp").                          |
| 2. When            | using this product  | . please observe the absolut   | te maximum ratings ar                            | nd the instructions for use outlined                  |
| in the             | se specification sh                                       | eets, as well as the precaution  | ons mentioned below.                             | Sharp assumes no responsibility                       |
| for an             | y damage resulting  | g from use of the product who<br>uded in these specification of  | iich does not comply w                           | rith the absolute maximum ratings                     |
|                    |   | duced in these specification s   | silects, and the precae                          | don's helitorica below.                               |
| •                  | cautions)   | decioned for year in the falls   | ouded application area                           | e ·   |
| ļ                  |   | designed for use in the follon<br>ent • Audio visual equipme   |  |   |
|                    |   | nication equipment (Termina  | _  |   |
|                    | 1   | hines · Computers  | ,  |   |
|                    | _ ~   | _  | lication areas is for eq                         | uipment listed in paragraphs                          |
|                    | (2) or (3), plea  | se be sure to observe the pro  | ecautions given in thos                          | se respective paragraphs.                             |
| •                  | the safety desig<br>and safety when<br>safety in function | easures, such as fail-safe dea<br>on of the overall system and<br>on this product is used for eq<br>on and precision, such as;<br>ion control and safety equip | equipment, should be<br>juipment which deman     | taken to ensure reliability ids high reliability and  |
|                    | • Traffic signa • Other safety                            | ls · Gas leakage sensor bi   |  |   |
| (                  |   | se this product for equipment netion and precision, such a   |  | emely high reliability                                |
|                    |   | ment • Telecommunication<br>rer control equipment • Me   |  | c lines)  |
| (                  |   | and consult with a Sharp sa<br>pretation of the above three  |  | ere are any questions                                 |
| 3. Please          | contact and consu   | lt with a Sharp sales repres   | sentative for any quest                          | ions about this product.                              |
|                    |   |  | DATE   |   |
| CUS                | TOMER'S APPRO   | OVAL   | PRESENTE<br>BY                                   | D K.H.  |
| D                  | ATE   |  | Depart   | himura,<br>ment General Manager of                    |
| B                  | ······································                    |  | Opto-E   | ering Dept.,II<br>Clectronic Devices Div.<br>OM Group |
|                    |   |  |  | CORPORATION   |

SHARP

**ELECTRONIC COMPONENTS** 

December 1, 1999

APPROVED BY:

DATE:



## 1. Application

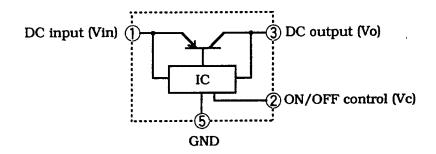
This specification applies to the outline and characteristics of tape packing type series regulator (linear type), Model No. PQ\*\*\*EZ01Z. Applied Model name

PQ015EZ01ZZ, PQ018EZ01ZZ, PQ025EZ01ZZ, PQ030EZ01ZZ, PQ033EZ01ZZ PQ015EZ01ZP, PQ018EZ01ZP, PQ025EZ01ZP, PQ030EZ01ZP, PQ033EZ01ZP

## Usage

PQ\*\*\*EZ01Z are the device for stabilization of DC positive output voltage with built-in ON/OFF function, the over current protection function, the overheat protection function and low consumption current at OFF-state (stand-by). These devices are possible to use in power supply circuit up to current capacity 1A.

## Block diagram



- 2. Outline: Refer to the attached sheet, Page 3.
- 3. Ratings and characteristics: Refer to the attached sheet, Page 4 to 7.
  - 3.1 Absolute maximum ratings
  - 3.2 Electrical characteristics
  - 3.3 Electrical characteristics measuring circuit
  - 3.4 Pd-Ta rating (Typical value)
- 4. Reliability: Refer to the attached sheet, Page 8, 9.
- 5. Outgoing inspection: Refer to the attached sheet, Page 9.



- 6. Supplement: Refer to the attached sheet, Page 10 to 15.
  - 6.1 Example of application
  - 6.2 Taping and reel packaging (PQ\*\*\*EZ01ZP)
  - 6.3 Sleeve packaging (PQ\*\*\*EZ01ZZ)
  - 6.4 ODS materials

This product shall not contain the following materials. Also, the following materials shall not be used in the production process for this product.

 $\begin{array}{c} \text{Materials for ODS} \ : \ \text{CFC}_S, \text{Halon, Carbon tetrachloride,} \\ 1.1.1\text{-Trichloroethane (Methylchloroform)} \end{array}$ 

6.5 Brominated flame retardants

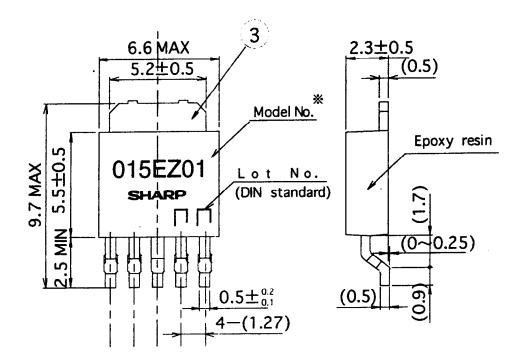
Specific brominated flame retardants such as the PBBOs and PBBs are not used in this device at all.

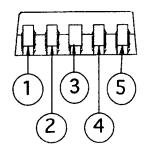
- 6.6 This product is not designed as electromagnetic and ionized-particle radiation resistant.
- 7. Notes: Refer to the attached sheet, Page 16 to 18.
  - 7.1 External connection
  - 7.2 Thermal protection design
  - 7.3 Static electricity
  - 7.4 Soldering
  - 7.5 For cleaning

Downloaded from Elcodis.com electronic components distributor



## 2. Outline





| Applied<br>model No. | Marked<br>model No. |
|----------------------|---------------------|
| PQ015EZ01ZZ          | 015EZ01             |
| PQ018EZ01ZZ          | 018EZ01             |
| PQ025EZ01ZZ          | 025EZ01             |
| PQ030EZ01ZZ          | 030EZ01             |
| PQ033EZ01ZZ          | 033EZ01             |
| PQ015EZ01ZZ          | 015EZ01             |
| PQ018EZ01ZZ          | 018EZ01             |
| PQ025EZ01ZZ          | 025EZ01             |
| PQ030EZ01ZZ          | 030EZ01             |
| PQ033EZ01ZZ          | 033EZ01             |

(Example of the marking in case of the PQ\*\*\*EZ01Z)

① DC input (Vin)

② ON/OFF control (Vc)

③ DC output (Vo)

4 NC

⑤ GND

·(): TYP.
· Unit: mm
· Scale: 5/1

· Lead finish: Solder plating

· Lead material : Cu

· Product mass: 0.3g



# 3. Ratings and characteristics

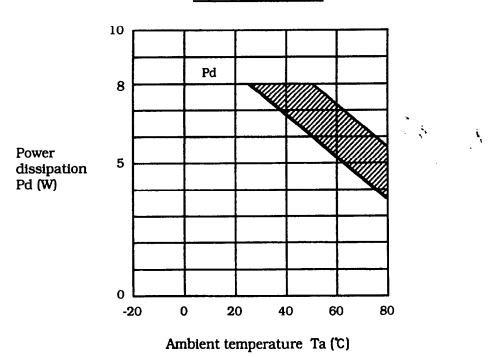
# 3.1 Absolute maximum ratings

Ta=25℃

| Parameter                   | Symbol | Rating      | Unit | Conditions      |
|-----------------------------|--------|-------------|------|-----------------|
| Input voltage (*1)          | Vin    | 10          | v    | -               |
| Output control voltage (*1) | Vc     | 10          | V    |                 |
| Output current              | Io     | 1           | A    |                 |
| Power dissipation (*2)      | Pd     | 8           | w    | Refer to Fig. 1 |
| Junction temperature (*3)   | Tj     | 150         | τ    |                 |
| Operating temperature       | Topr   | -40 to +85  | τ    |                 |
| Storage temperature         | Tstg   | -40 to +150 | τ    |                 |
| Soldering temperature       | Tsol   | 260         | r    | For 10 s        |

- (\*1) All are open except GND and applicable terminals.
- (\*2) Pd: With infinite heat sink
- (\*3) There is case that over heat protection operates at the condition Tj=125℃ to 150℃

Fig. 1 Pd - Ta rating



Pd: With infinite heat sink

(Note) There is case that over heat protection function operates at oblique line portion.

## 3.2 Electrical characteristics

Unless otherwise specified condition shall be Vin=Vo(TYP)+1V, Io=0.5mA, Vc=2.7V, Ta=25°C

| Parameter                                 | Symbol   | MIN. | TYP.            | MAX. | Unit | Conditions                                |
|---|----------|------|-----------------|------|------|---|
| Input voltage                             | Vin      | 2.35 | -               | 10   | v    |   |
| Output voltage                            | Vo       | Re   | Refer to list 1 |      |      |   |
| Load regulation                           | RegL     | -    | 0.2             | 2.0  | %    | Io=5mA to 1A                              |
| Line regulation                           | RegI     | -    | 0.1             | 1.0  | %/V  | Vin=Vo(TYP)+1V<br>to Vo(TYP)+6V<br>Io=5mA |
| Temperature coefficient of output voltage | TcVo     | -    | ±0.01           | -    | %/℃  | Io=5mA<br>Tj=0 to 125℃                    |
| Ripple rejection                          | RR       | 45   | 60              | •    | đВ   | Refer to Fig.3                            |
| Dropout voltage                           | Vi-o     | -    | 0.2             | 0.5  | v    | (*5), Io=0.5A                             |
| On-state voltage for control              | Vc (on)  | 2.0  | -               | •    | v    |   |
| On-state current for control              | Ic (on)  | -    | -               | 200  | μΑ   |   |
| Off-state voltage for control             | Vc (off) | -    | -               | 0.8  | v    |   |
| Off-state current for control             | Ic (off) | •    | -               | 2    | μΑ   | Vc=0.4V                                   |
| Quiescent current                         | Iq       | -    | 1               | 2    | mA   | Io=0A                                     |
| Output off-state consumption current      | Iqs      | -    | -               | 5    | μA   | Io=0A<br>Vc=0.4V                          |

<sup>(\*4)</sup> Applied to PQ030EZ01Z and PQ033EZ01Z.

(\*5) Input voltage when output voltage falls 0.95Vo by input voltage falling down.

## List 1 Output voltage

| Model No.  | Symbol | MIN   | TYP | MAX   | Unit | Condition |
|------------|--------|-------|-----|-------|------|-----------|
| PQ015EZ01Z | Vo     | 1.45  | 1.5 | 1.55  | V    |           |
| PQ018EZ01Z | Vo     | 1.75  | 1.8 | 1.85  | v    |           |
| PQ025EZ01Z | Vo     | 2.438 | 2.5 | 2.562 | V    |           |
| PQ030EZ01Z | Vo     | 2.925 | 3.0 | 3.075 | V    |           |
| PQ033EZ01Z | Vo     | 3.218 | 3.3 | 3.382 | V    |           |

<sup>(\*6)</sup> In case that the control terminal (3 pin) is non-connection, output voltage should be OFF state.



# 3.3 Electrical characteristics measuring circuit

# Fig. 2 Standard measuring circuit of Regulator portion

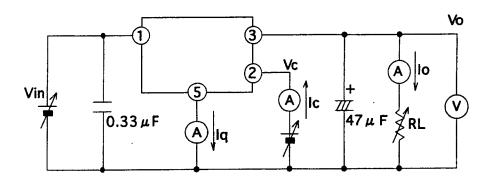
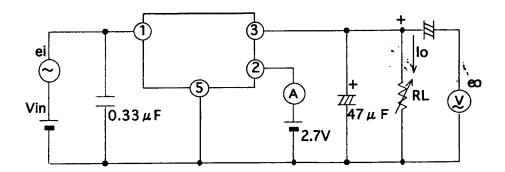


Fig. 3 Standard measuring circuit of critical rate of ripple rejection

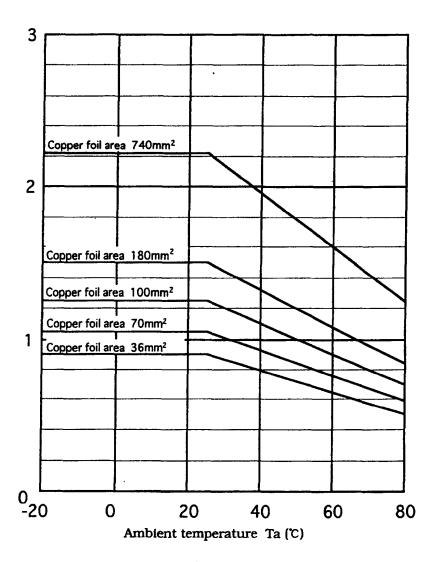
f=120Hz sine wave ei(rms)=0.5V Vin=Vo(TYP)+1V Io=0.3A RR=20 log {ei(rms)/eo(rms)}

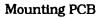


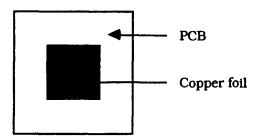
Power

dissipation Pd (W)

3.4 Pd - Ta rating (Typical value)







Material: Glass-cloth epoxy resin

Size :  $50 \times 50 \times 1.6$ mm Thickness of copper :  $35 \mu$ m

# SHARP CORPORATION



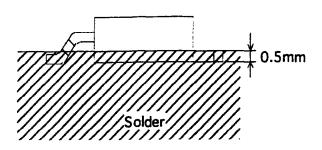
# 4. Reliability

The reliability of products shall satisfy items listed below.

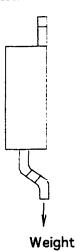
Confidence level: 90% LTPD: 10%/20%

| Test Items                                     | Test Conditions  | Failure Judgement<br>Criteria   | Samples (n) Defective(C) |
|--|--|---|--------------------------|
| Temperature cycling                            | 1 cycle -40°C to +150°C<br>(30min) (30min)<br>20 cycles test   | Vo <l×0.8< td=""><td>n=22, C=0</td></l×0.8<>  | n=22, C=0                |
| Humidity<br>(Steady State)                     | +60°C,90%RH, 1000h   | Vo>U×1.2  | n=22, C=0                |
| Damp Heat cyclic                               | 1 cycle: -20°C to 70°C (2h) (2h) Transfer time between high and low temp. is 1h. 40 cycles test, 90%RH | RegL>U×1.2 RegI>U×1.2   | n=22, C=0                |
| High temp. storage                             | +150°C, 1000h  | RR <l×0.8< td=""><td>n=22, C=0</td></l×0.8<>  | n=22, C=0                |
| Low temp. storage                              | -40°C, 1000h   | Vi-o>UX1.2 *4   | n=22, C=0                |
| Operation life                                 | Ta=25°C, Pd=0.8W, 1000h  | VI-0>UX1.2 -4   | n=22, C=0                |
| Mechanical shock                               | 15km/s <sup>2</sup> , 0.5ms<br>3 times/ $\pm X$ , $\pm Y$ , $\pm Z$                                    |   | n=11, C=0                |
| Vibration<br>(Variable<br>frequency)           | 200m/s <sup>2</sup><br>100 to 2000 to 100Hz/4 min<br>4 times/ X, Y, Z direction                        | U: Upper<br>specification   | n=11, C=0                |
| Electrostatic<br>discharge                     | ±250V, 200pF, 0Ω<br>Between GND and each<br>terminal/ 3 times  | limit  L: Lower  specification  | n=11, C=0                |
| Soldering heat                                 | 260°C, 10 s, Dip up to<br>0.5mm from resin portion *1  | inmt  | n=11, C=0                |
| Robustness of<br>Termination<br>(Tensile test) | Weight: 10N<br>10 s/ each terminal<br>*2   | Failure if it has   | n=11, C=0                |
| Robustness of<br>Termination<br>(Bending test) | Weight: 2.5N<br>0° ~90° ~0° ~-90° ~0°<br>each terminal *3  | breakdown and<br>loosened pin.<br>*5  | n=11, C=0                |
| Solderability                                  | 230±5°C, 5±0.5 s<br>Use rogin flux *1  | Failure if solder shall not be adhere at the area of 95% or more dipped portion. *6 | n=11, C=0                |

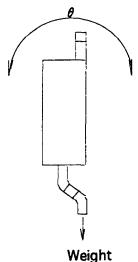
\*1 Soldering area is shown below.



\*2 Terminal tensile direction is shown below.



\*3 Terminal bending direction is shown below.



- \*4 Applied to PQ030EZ01Z and PQ033EZ01Z.
- \*5 Except for the bending of terminal.
- \*6 Except for the portion within 0.5mm from the interface between the heat sink and the resin portion, and the side surface of heat sink.

5. Outgoing inspection

TABLE II-A single sampling plans for normal inspection based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

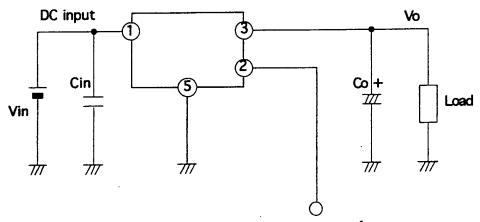
| Defect          | Inspection items                              | AQL (%) | Judgement<br>criteria |
|-----------------|---|---------|-----------------------|
| Major<br>defect | Electrical characteristics Unreadable marking | 0.1     | Depend on the         |
| Minor<br>defect | Appearance<br>Dimensions                      | 0.4     | specification         |

# SHARP CORPORATION

| December 1, 1999 | December 1, 1999 | PAGE | 10/18

# 6. Supplement

# 6.1 Example of application



ON-OFF signal

High: Output ON
Low or Open: Output OFF



## 6.2 Packing specifications (PQ\*\*\*EZ01ZP)

### 6.2.1 Packing conditions

(1) Tape structure and Dimensions (Refer to Fig. A)

The tape shall have a structure in which a cover tape is sealed heatpressed on the carrier tape of polystyrene emboss protect against static electricity. Dimensions are shown Fig. A.

(2) Reel structure and Dimensions (Refer to Fig.B)

The reel shall be made of polystyrene. Dimensions are shown Fig. B.

(3) Direction of product insertion (Refer to Fig. C)

Product direction in carrier tape shall direct to the radiate fin of product at the hole side on the tape.

## 6.2.2 Tape characteristics

(1) Adhesiveness of cover tape

The peel-back force between carrier tape and cover tape shall be 0.1N to 0.8N for the angle from 160° to 180°. (Tape speed: 5mm/s)

(2) Bending strength

Sealed tape: Bended tape radius shall be more than 30mm.

If bended tape radius is less than 30mm.

there is case that cover tape come off carrier tape.

Carrier tape: Bended tape radius shall be more than 15mm.

## 6.2.3 Rolling method and quantity

(1) Rolling method

Wind the tape back on the reel so that the cover tape will be outside the tape. Attach more than 20 pitch of empty cavities to the trailer and attach more than 10 pitch of empty cavities to the leader of the tape and fix the both ends with adhesive tape.

(2) Quantity

One reel shall contain 3000 pcs.

#### 6.2.4 Indication

(1) Reel

The reel shall be pasted label with following information.

- \* Model No. \* Number of pieces contained \* Production date
- (2) Package case

The outer packaging case shall be marked with following information.

\* Model No. \* Number of pieces contained \* Inspection date

## 6.2.5 Storage condition

Taped products shall be stored at the temperature lower than 5 to 30°C and the humidities lower than 70%RH. If taped products aren't used longer than for 10days, Please rewind the tape pulled out and storage.

#### **6.2.6** Others

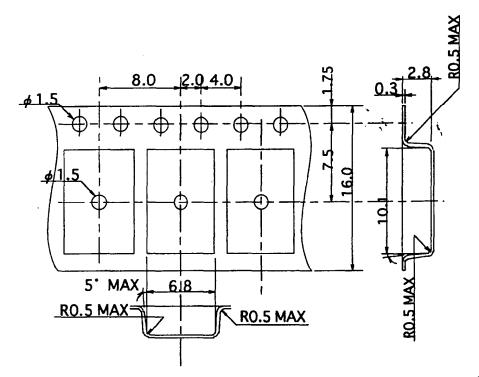
(1) joint of tape

The cover tape and carrier tape in one reel shall be jointless.

(2) The way to repair taped failure devices

The way to repair taped failure devices cut a bottom of carrier tape with a cutter, and after replacing to good devices, the cutting portion shall be sealed with adhesive tape.

Fig. A Tape structure and Dimensions



Dimensions: TYP. value

Unit: mm

Fig. B Reel structure and Dimensions

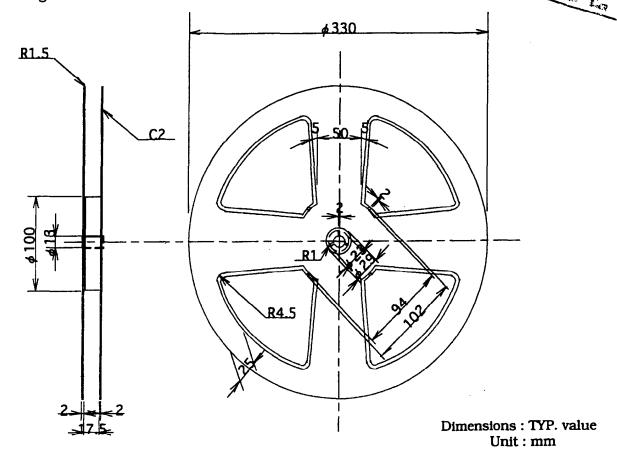
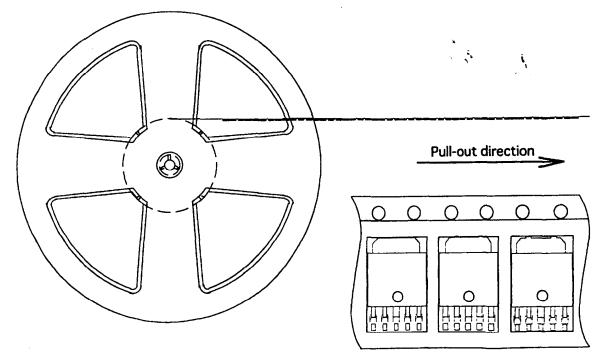
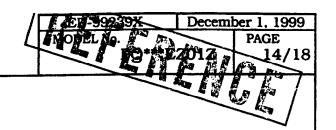


Fig. C Direction of product insertion





## 6.3 Sleeve packaging (PQ\*\*\*EZ01ZZ)

## 6.3.1 Packing conditions

(1) Sleeve structure and Dimensions (Refer to Fig. D)

The sleeve shall be made of high inpuct polethylene (Plastics with preventing static electricity). Dimensions are shown Fig. D.

- (2) The packing case shall be made of corrugated cardboard. Dimensions are shown Fig. F.
- (3) Stopper structure

The stopper shall be made of styrene butadiene rubber.

## 6.3.2 Packaging method and quantity

(1) Packaging method

Max. 75pcs. of products shall be packaged in a sleeve and both of sleeve edges shall be fixed by stoppers. Fix the packing case by kraft tape.

(2) Quantity (Refer to Fig. E)

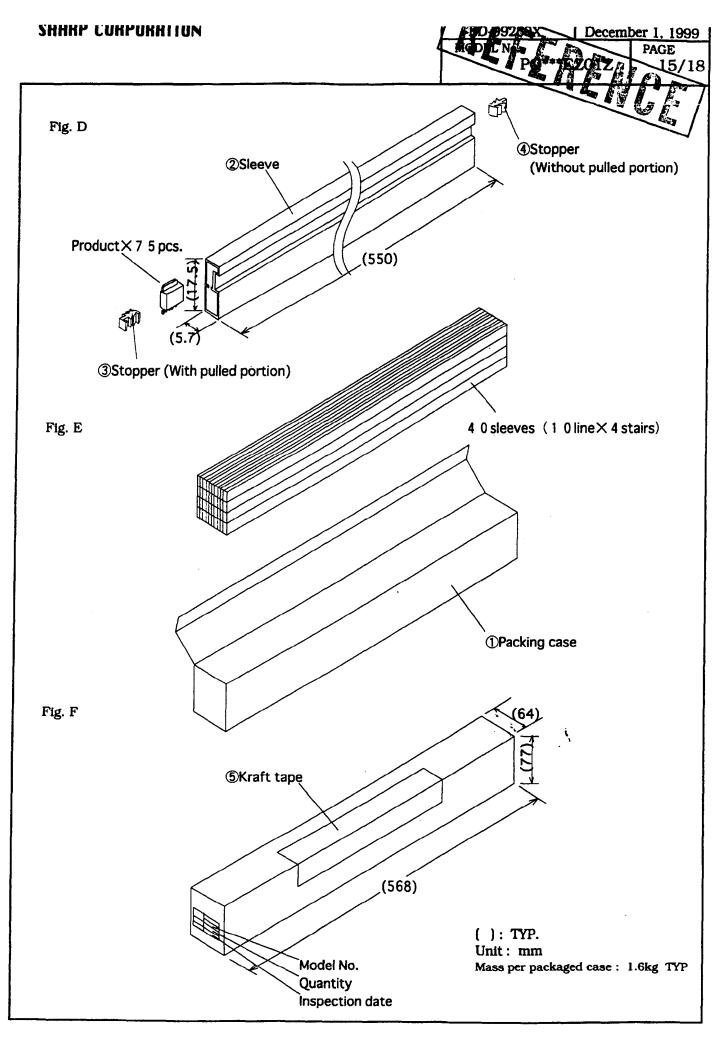
One package shall contain 3000pcs./package.

### 6.3.3 Indication

(1) Packing case

The packing case shall be marked with following information.

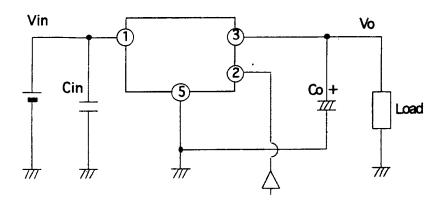
\* Model No. \* Number of pieces contained \* Inspection date





#### 7. Notes

## 7.1 External connection



C-MOS or TTL

- (1) Please perform shortest wiring for connection between Cin, Co and the individual terminal. There is case that oscillation occurs easily by kinds of capacitor and capacity. Before you use this device, you should confirm output voltage on your use mounting state.
- (2) The input terminal for ON/OFF output control; ② is compatible with LS-TTL, and direct driving by TTL or C-MOS standard logic (RCA 4000 series) is also available. In case that ON/OFF terminal is not used, we recommend to connect the ON/OFF terminal directly to the input terminal; ① input voltage.
- (3) As voltage application under conditions that the device pin is inserted divergently or reversely, may occur the degradation of characteristics or breakdown of the device, please avoid it absolutely.

## 7.2 Thermal protection design

Internal power dissipation (Pd) of device is obtained by the following equation.

 $Pd=Io\times(Vin-Vo)+Vin\times Iq$ 

If the maximum operating temperature and Pd (MAX.) when the device is operating are determined, use such a heat sink as allows the device to operate within the safety operation area specified by the derating curve in para. 3.4. Insufficient radiation gives an unfavorable influence to the normal operation and reliability of the device. In the case of no passage within the safety operational territory illustrated by the derating curve, the overheat protection circuit operates to let output fall down, please avoid keeping such condition for a long time.



## 7.3 Static electricity

Good caution must be exercised against static electricity since this device consists of a bipolar IC. Following are some examples of preventive measures against excessive voltages such as caused by static electricity.

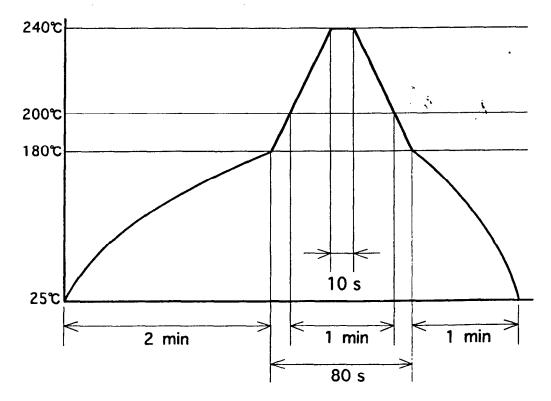
- (a) Human body must be grounded to discharge the static electricity from the body or cloth.
- (b) Anything that is in contact with the device such as workbench, inserter, or measuring instrument must be grounded.
- (c) Use a solder dip basin with a minimum leak current (isolation resistance  $10M\Omega$  or more) from the commercial power supply. Also the solder dip basin must be grounded.

### 7.4 Soldering

## (1) Reflow soldering

It is recommended that within two times soldering be done at the temperature and the time within the temperature profile as shown in the figure. (The temperature shown in the figure is fin portion temperature of the device.) It is recommended that the second reflow become at the device which is the room temperature.

- (a) An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. The temperature of resin portion should be with in the temperature profile below.
- (b) The temperature sloping when soldering-reflow is 4°C/s or less.



### SHARP CORPORATION



# (2) Dip soldering

We recommend that solder dip should be 260°C or less (Solder temp.) within 10s and 1 time only. Please obey the note items below concerning solder reflow.

- (a) After solder dip, please do cooling naturally.
- (b) Please shall not give the mechanical stress or the impact stress to the device.

In advance, please confirm fully the dip soldering conditions etc. in the actual application in order to avoid any soldering bridge.

## (3) Hand soldering

This device is basically designed for the soldering such as reflow soldering or dip soldering. In case when hand soldering is reluctantly needed for modification etc., it is recommended that only one hand soldering should be done at 260°C or less of soldering iron edge temperature, for 10s or less. Please be careful not to touch soldering iron edge to leads directly etc. in order not to give any stress to the leads.

Even within the above conditions regarding solder reflow, solder dip or hand soldering there is the possibility that the stress given to the terminals by the deformation of PCB makes the wire in the device package cut. In advance, please confirm fully at the actual application.

## 7.5 For cleaning

(1) Solvent cleaning: Solvent temperature 45°C or less Immersion for 3 min or less

(2) Ultrasonic cleaning: The effect to device by ultrasonic cleaning differs

by cleaning bath size, ultrasonic power

output, cleaning time, PCB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting

the ultrasonic cleaning.

(3) Applicable solvent: Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

In case when the other solvent is used, there are cases that the packaging resin is eroded. Please use the other solvent after thorough confirmation is performed in actual using condition.